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hereto, where underlining indicates added text and bracketing indicates removed text. No new matter has been added. Applicants respectfully submit that claim 16 as now rewritten is in a condition for allowance.

Since claims 17 to 33 depend from claim 16, either directly or indirectly, those claims are allowable for the same reason(s) as claim 16.

Accordingly, withdrawal of the rejections of claims 16 to 33 under 35 U.S.C. §112, second paragraph, is respectfully requested.

Regarding paragraph three (3) of the Office Action, claim 1 was rejected under 35 U.S.C. §102(b) as being anticipated by Patent Abstracts of Japan, Publication No. 57-149784 to Tadao (the "Tadao reference"). Applicants respectfully submit that claim 1 was canceled in Applicants' Preliminary Amendment dated and filed on April 18, 2000. Accordingly, the rejection of claim 1 is rendered moot. Further, in the event the Examiner intended to suggest claim 16, not claim 1, is anticipated by the Tadao reference, Applicants respectfully submit that the Tadao reference does not identically describe (as it must to anticipate) or even suggest disposing a temperature sensor directly on the semiconductor laser chip for measuring its operating temperature, as in claim 16. Furthermore, the Tadao reference does not identically describe or even suggest integrating a temperature sensor in the semiconductor laser chip, as in claim 16. In contrast, the Tadao reference recites a laser diode element, a temperature detection element and an electronic cooling element being formed together on a same chip and fixed to a holding mount, in order to obtain a stable luminous wavelength. Accordingly, Applicants respectfully submit that claim 16 is allowable over the Tadao reference. And, since claims 17 to 33 depend from claim 16, either directly or indirectly, those claims are allowable for the same reasons as claim 16.

In summary, it is respectfully submitted that all of claims 16 to 33 of the present application are allowable for the foregoing reasons.

CONCLUSION

In view of all of the above, it is believed that the rejections of claims 16 to 33 under 35 U.S.C. §112, second paragraph, have been obviated. Further, it is believed that the rejection of claim 1, which had been canceled earlier, under 35 U.S.C. §102(b) in view of the Tadao reference is moot; moreover, in view of all of the above, it is believed that the Tadao reference does not identically describe (as it must to anticipate) or even suggest the invention as claimed in any of claims 16 to 33. Accordingly, it is respectfully submitted that all claims

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16 to 33 are allowable.

It is therefore respectfully requested that the rejections be reconsidered and withdrawn, and that the present application issue as early as possible.

Respectfully Submitted,

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U.S. PAT. APP. SER. NO. 09/529,700

ATT. DOCKET NO. 2345/119

VERSION SHOWING CHANGES MADE

Please amend without prejudice claim 16 as follows:

16. (Amended) A semiconductor laser comprising:

a semiconductor laser chip; and
at least one temperature sensor configured to be one of disposed directly on [or] and
integrated in the semiconductor laser chip for measuring an operating temperature.